

[Name of Document] Abstract

[Title of Invention] SHEET FOR SEMICONDUCTOR PROCESSING

A sheet (1) for semiconductor processing, the sheet (1)
5 comprising a base material (2) and a pressure sensitive adhesive
layer (3) laminated on at least one surface of the base material
(2), the pressure sensitive adhesive layer (3) being formed of
a pressure sensitive adhesive composition, the pressure
sensitive adhesive composition containing a polymer having a
10 salt and an energy ray curable group and an energy ray curable
pressure sensitive adhesive component (excluding the above
polymer). The sheet (1) for semiconductor processing can
suppress contamination of an adherend at the time of peeling
after energy ray irradiation while exhibiting a sufficient
15 antistatic property.